

Title (en)

METHOD FOR THE PRODUCTION OF AN ELECTRONIC ASSEMBLY, AND ELECTRONIC ASSEMBLY

Title (de)

VERFAHREN ZUR HERSTELLUNG EINER ELEKTRONISCHEN BAUGRUPPE SOWIE ELEKTRONISCHE BAUGRUPPE

Title (fr)

PROCÉDÉ DE FABRICATION D'UN MODULE ÉLECTRONIQUE ET MODULE ÉLECTRONIQUE

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Application

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Abstract (en)

[origin: WO2008119586A1] The invention relates to a method for the production of an electronic assembly (21), comprising at least one electronic component (9), wherein, in a first step, the at least one electronic component (9) is affixed to an insulating layer (5) of a conductive film (1), wherein the active side of the electronic component (9) is positioned toward the conductive film (1). In a second step, the conductive film (1) having the at least one electronic component (9) attached thereon is laminated onto a printed circuit board carrier (13), wherein the at least one electronic component (9) is positioned toward the printed circuit board carrier (13). As a final step conductors (15) are formed by the structuring of the conductive film (1), and the at least one electronic component (9) is contacted. The invention further relates to an electronic assembly, comprising at least one electronic component (9) that is connected to a conductor structure on a printed circuit board carrier (13). The at least one electronic component (9) is embedded in the printed circuit board carrier (13), and the conductor structure (15, 27) is disposed on the surface of the printed circuit board (23).

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